

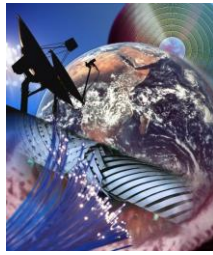
Beyond Silicon...

Advanced Power Electronics for FACTS Technology

Jerry Melcher

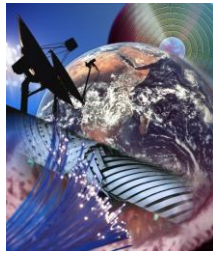
APE Initiative Lead

Energy Delivery and Utilization



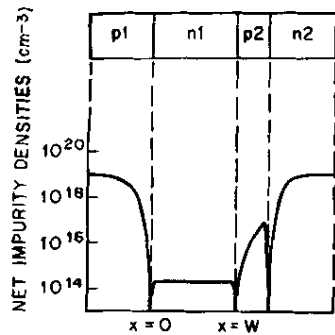
Initiative Objectives

- Why are we doing this?
- Where are we going?

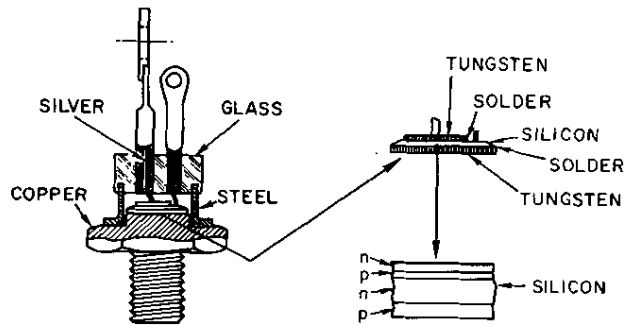


Power Electronics

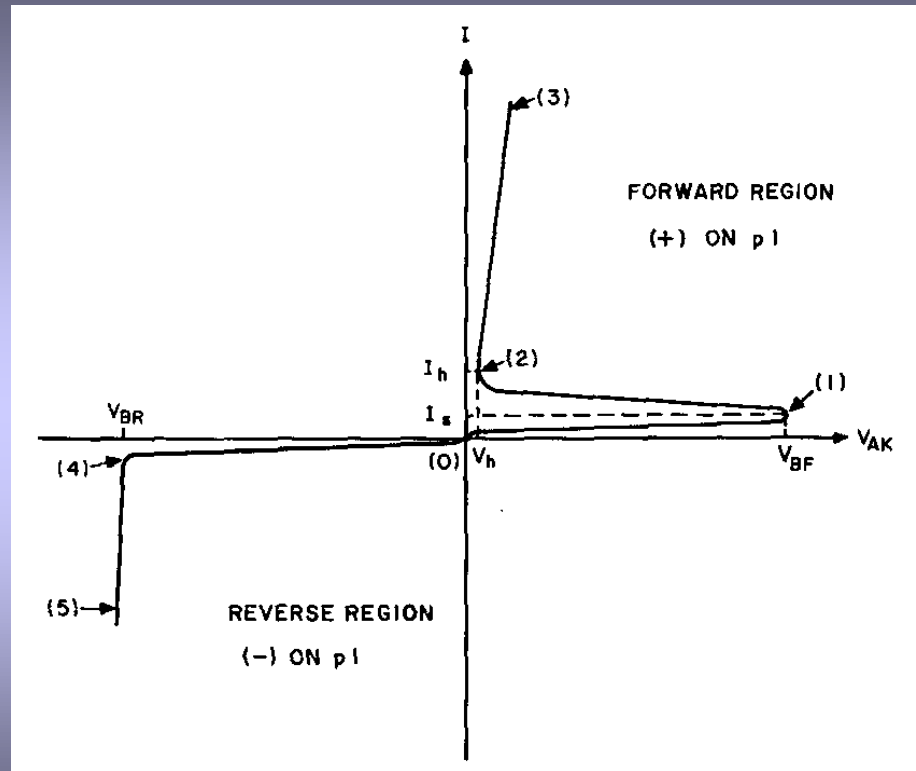
The Thyristor

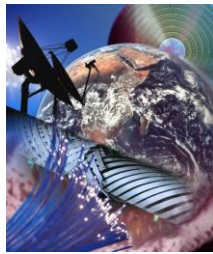


(a)



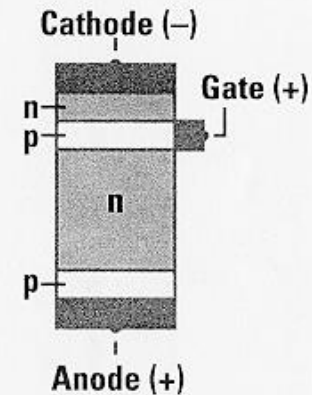
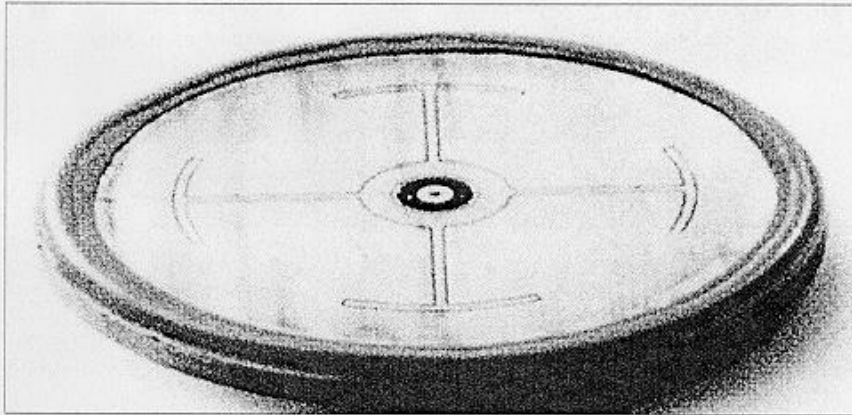
(b)





Thyristor - SCR

Semiconductor-Controlled Rectifier (SCR)



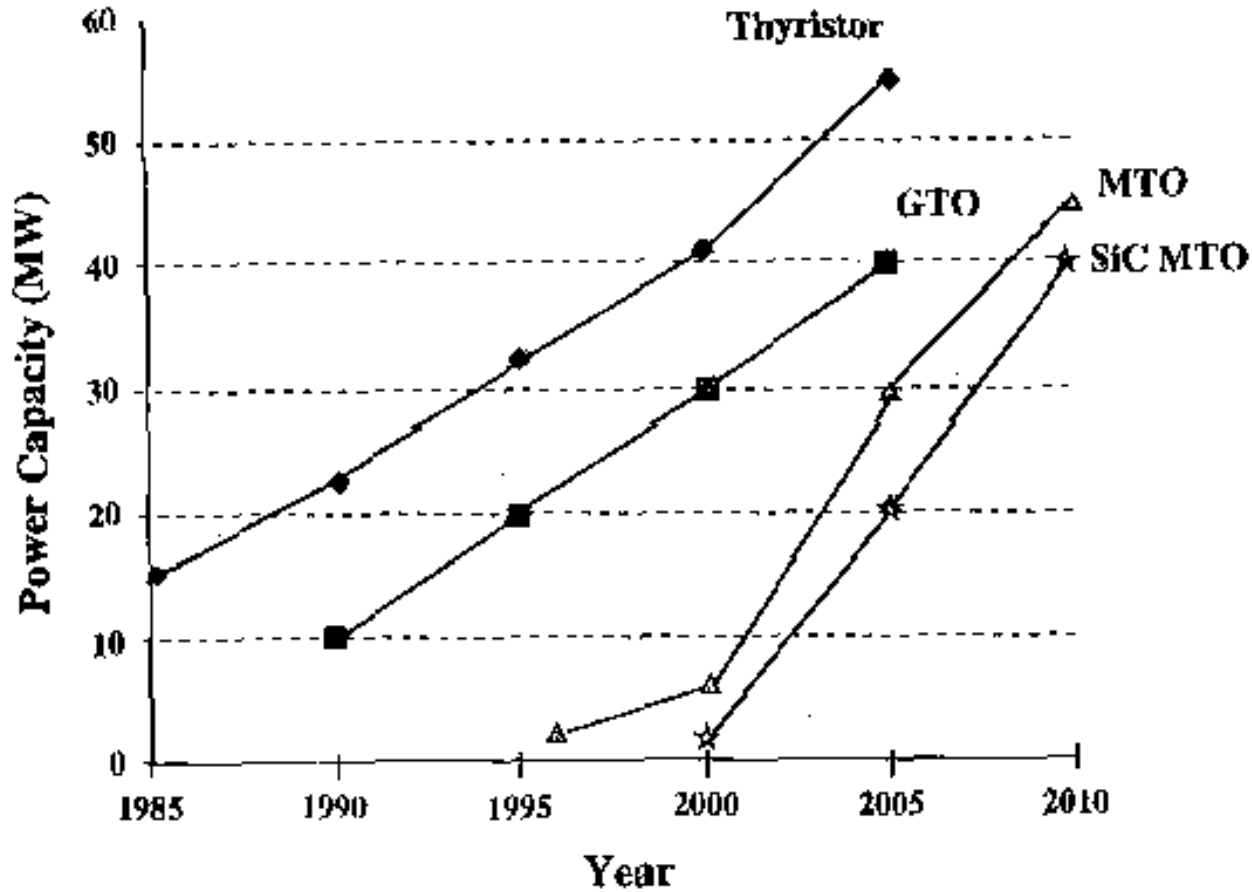
Advantage: solid state power control

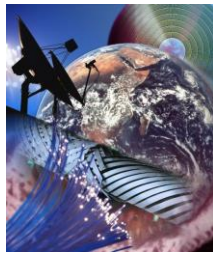
Disadvantage: once turned on, an SCR continues to conduct regardless of voltage

Usage Boundaries: <6000 V, 2000–4000 A



Power Progress for Si



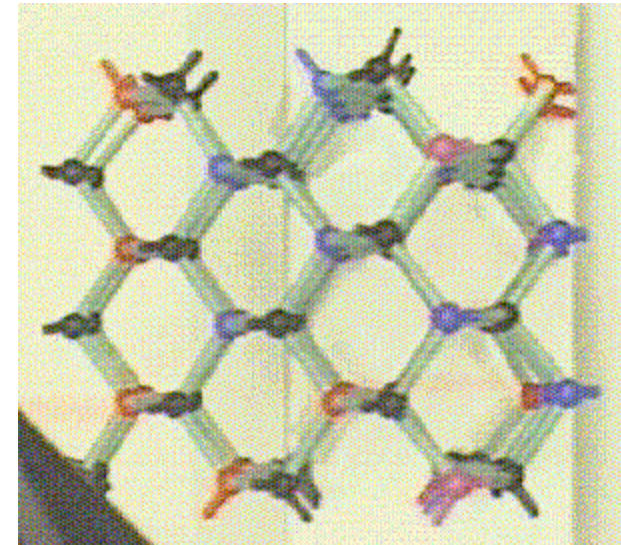
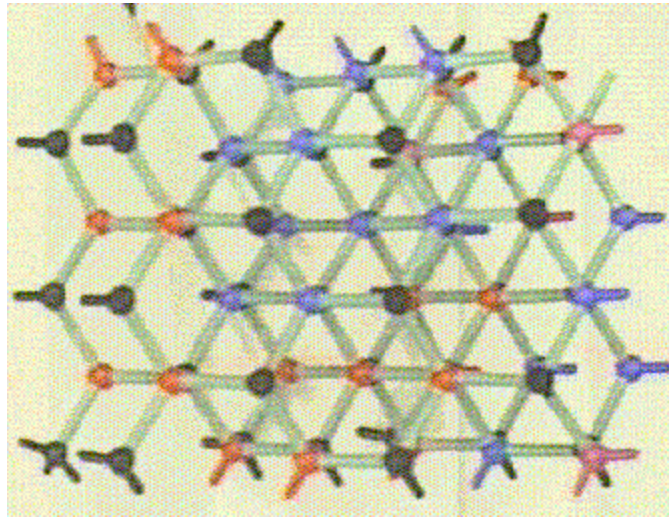
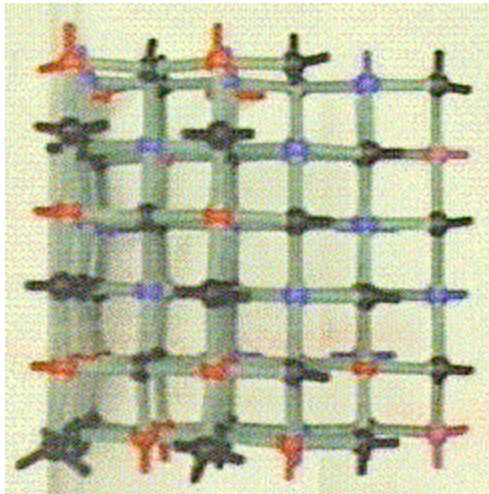


Initiative Objectives

- Why are we doing this?
 - *Si Power Devices are Reaching Their Fundamental Limits of Performance.*
- Where are we going?



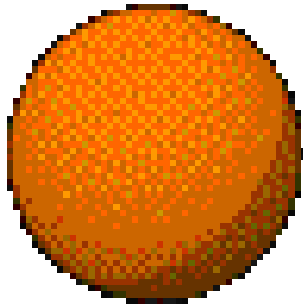
The “Diamond” Structure



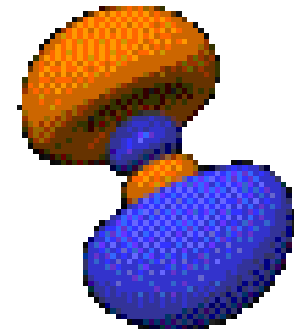
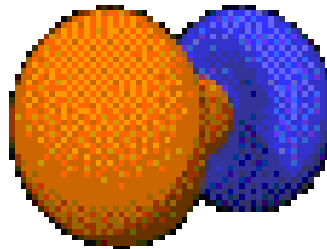


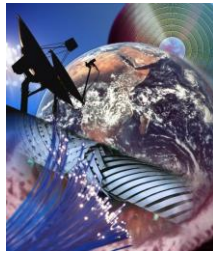
Si Electrons

3s

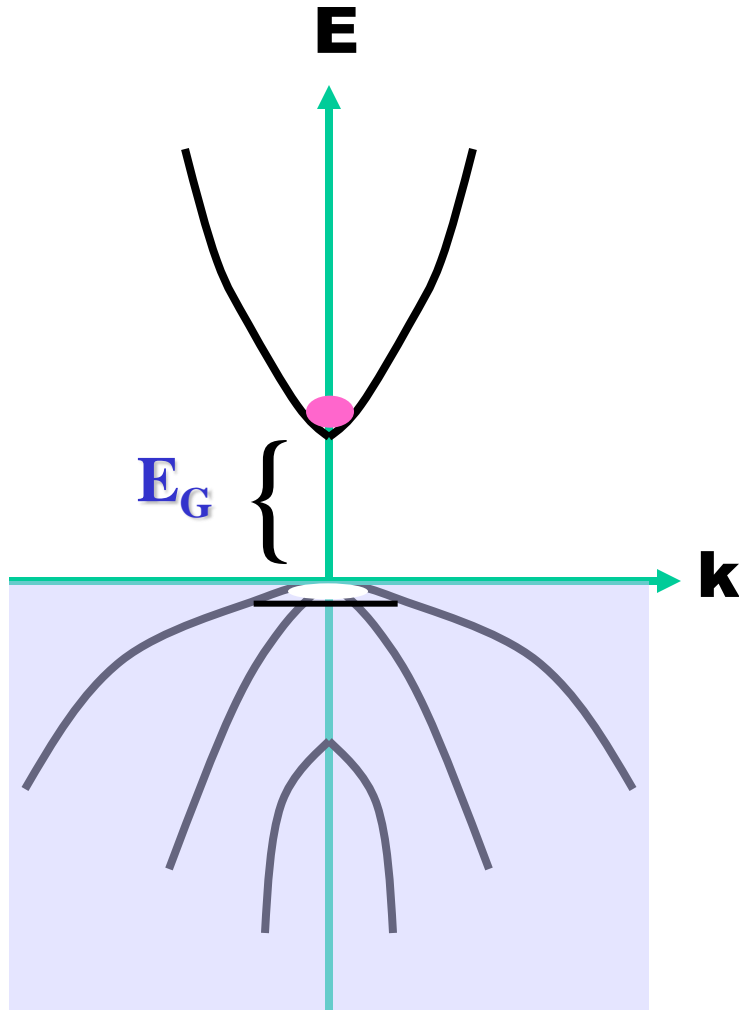


3p





Physics of Semiconductors

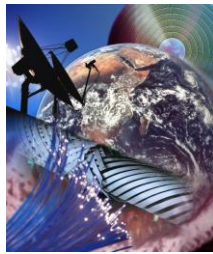


k•p Perturbation Theory

$$\varepsilon_n(\mathbf{k}) = \varepsilon_n(0) + \frac{\hbar^2 k^2}{2m} + \frac{\hbar^2}{m^2} \sum_{j \neq n} \frac{|\langle n0 | \mathbf{k} \cdot \mathbf{p} | j0 \rangle|^2}{\varepsilon_n(0) - \varepsilon_j(0)},$$

$$\frac{m}{m^*} = 1 + \frac{2}{m} \sum_{j \neq n} \frac{|\langle n0 | \mathbf{p} \mathbf{p} | j0 \rangle|}{\varepsilon_n(0) - \varepsilon_j(0)},$$

$$\frac{m}{m^*} \approx \frac{2}{mE_G} \sum_v |\langle c | \mathbf{p} \mathbf{p} | v \rangle|$$



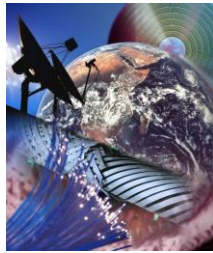
Chemistry of Semiconductors

H																	He
Li	Be											B	C	N	O	F	Ne
Na	Mg											Al	Si	P	S	Cl	Ar
K	Ca	Sc	Ti	V	Cr	Mn	Fe	Co	Ni	Cu	Zn	Ga	Ge	As	Se	Br	Kr
Rb	Sr	Y	Zr	Nb	Mo	Tc	Ru	Rh	Pd	Ag	Cd	In	Sn	Sb	Te	I	Xe
Cs	Ba		Hf	Ta	W	Re	Os	Ir	Pt	Au	Hg	Tl	Pb	Bi	Po	At	Rn
Fr	Ra		Unq	Unp	Unh	Uns	Uno	Une	Uun	Uuu	Uub						
		La	Ce	Pr	Nd	Pm	Sm	Eu	Gd	Tb	Dy	Ho	Er	Tm	Yb	Lu	
		Ac	Th	Pa	U	Np	Pu	Am	Cm	Bk	Cf	Es	Fm	Md	No	Lr	



Initiative Objectives

- Why are we doing this?
 - *Si Power Devices are Reaching Their Fundamental Limits of Performance.*
- Where are we going?
 - *SiC and GaN have Breakdown Electrical Fields ~10 Times Higher than Si. Both 4 Times the Forward Current...at the Same Unit Cost! (maybe)*



EPRI/DARPA

13-18 M\$, 3 Years

- Nasa-Lewis SiC
- Northrup-Grumman SiC
- Vanderbilt University SiC
- Silicon Power Corp SiC

- University of Florida GaN
- Cal Tech GaN

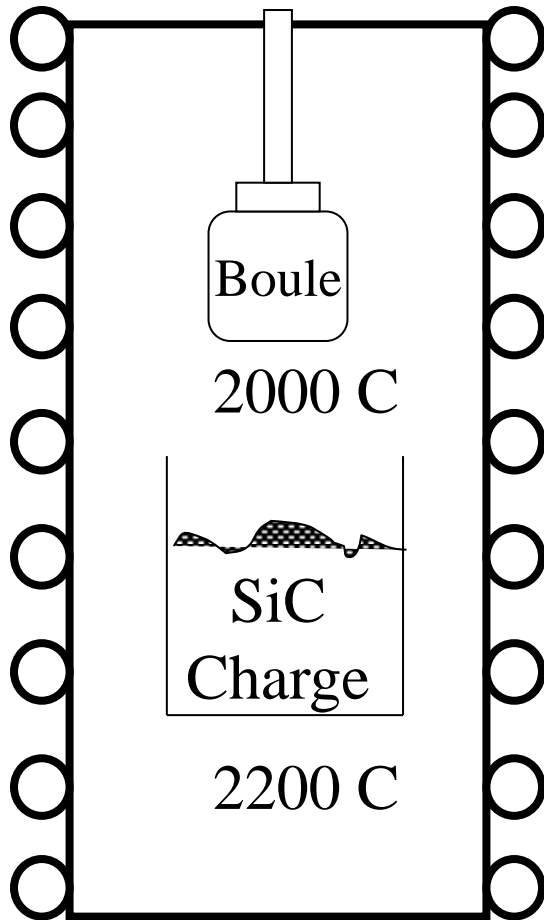


Advantages of Post-Silicon Materials

<u>Property</u>	<u>Si</u>	<u>CVD</u>			<u>GaN</u>	
		<u>3C SiC</u>	<u>(6C SiC)</u>	<u>Diamond</u>		
Bandgap (300K) Voltage	1.1		2.2 (2.9)	5.5	3.4	Blocking
Maximum Operating Power Flow Temp (K)	500		>900 (>1000)	1400	>800	Limits
Breakdown Voltage Maximum (Eb, 10⁶ V/cm) Capacity	0.3		4	10	5	Power
Hole Mobility Switching Speed (RT, cm²/Vs)	600		40	1600	200	
Thermal Conductivity Rate (C_T, w/cm)	1.5		5	20	1.3	Cooling

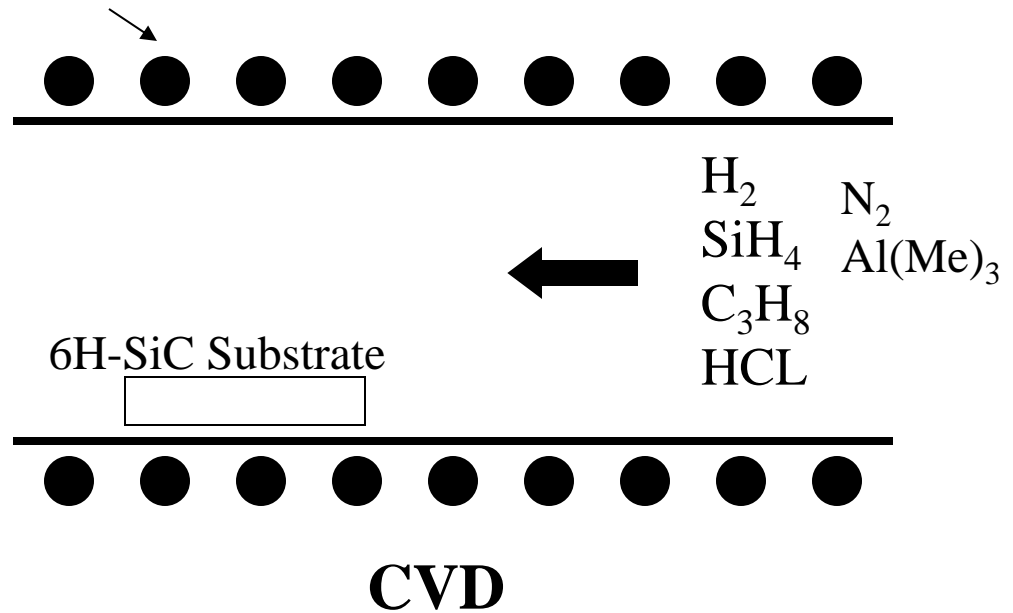


SiC Growth

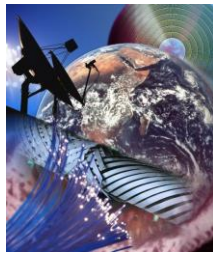


Sublimation

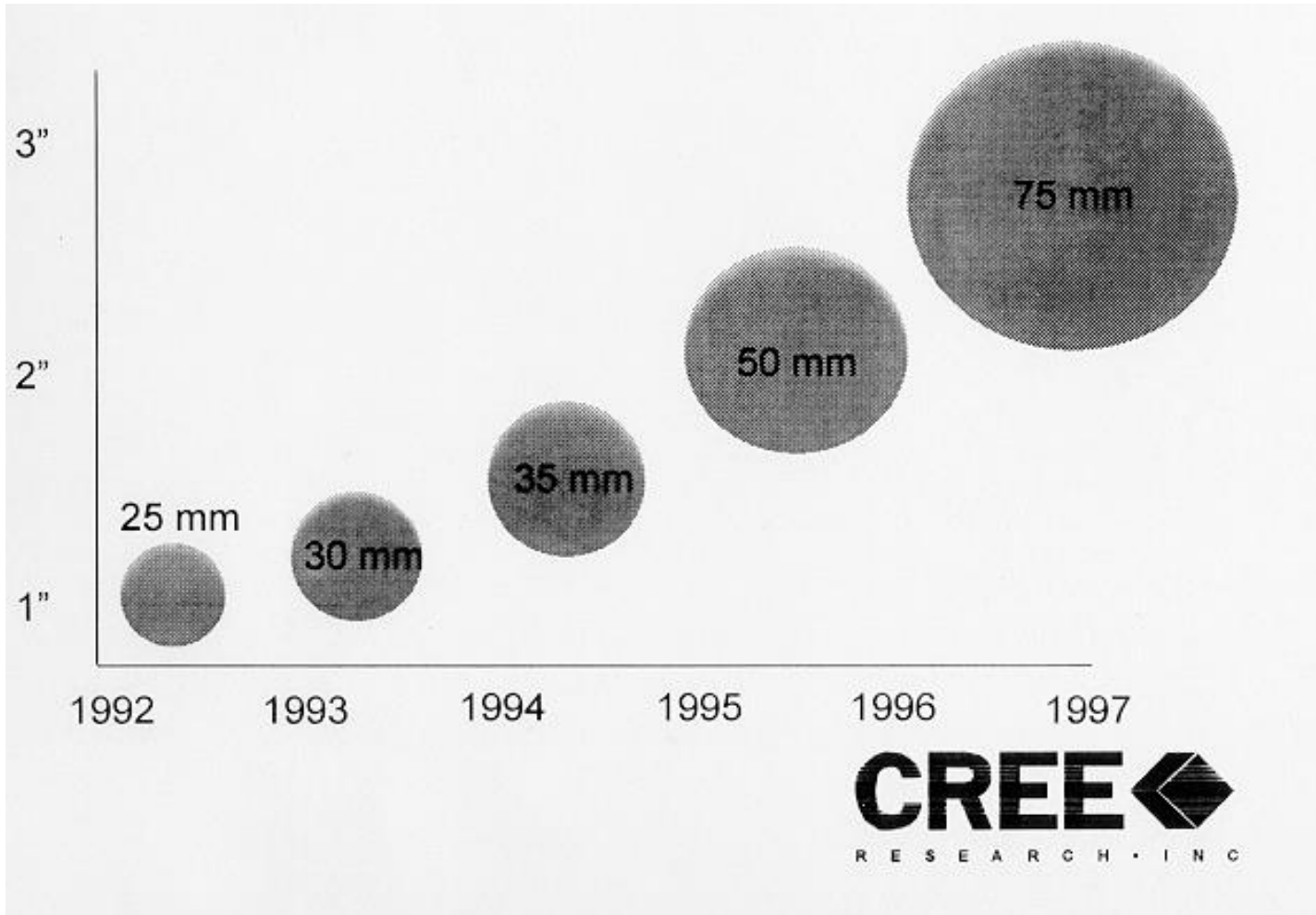
RF Coils

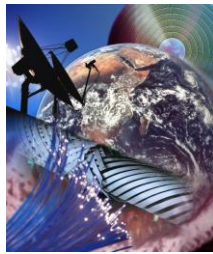


CVD

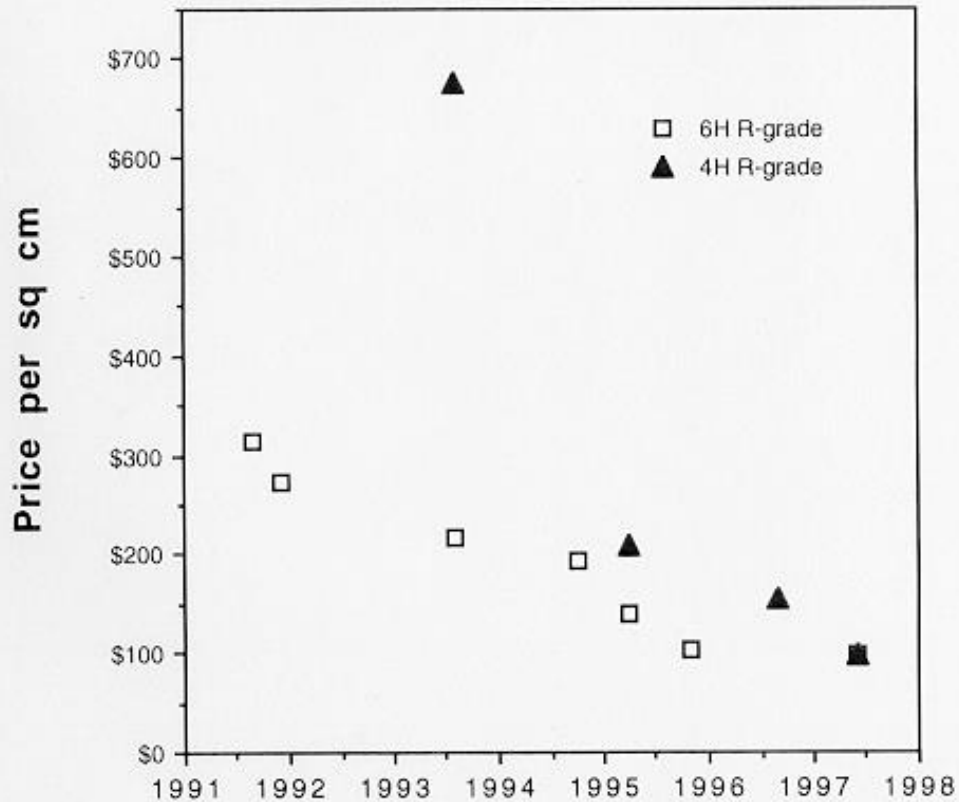


SiC: Progress in Wafer Size



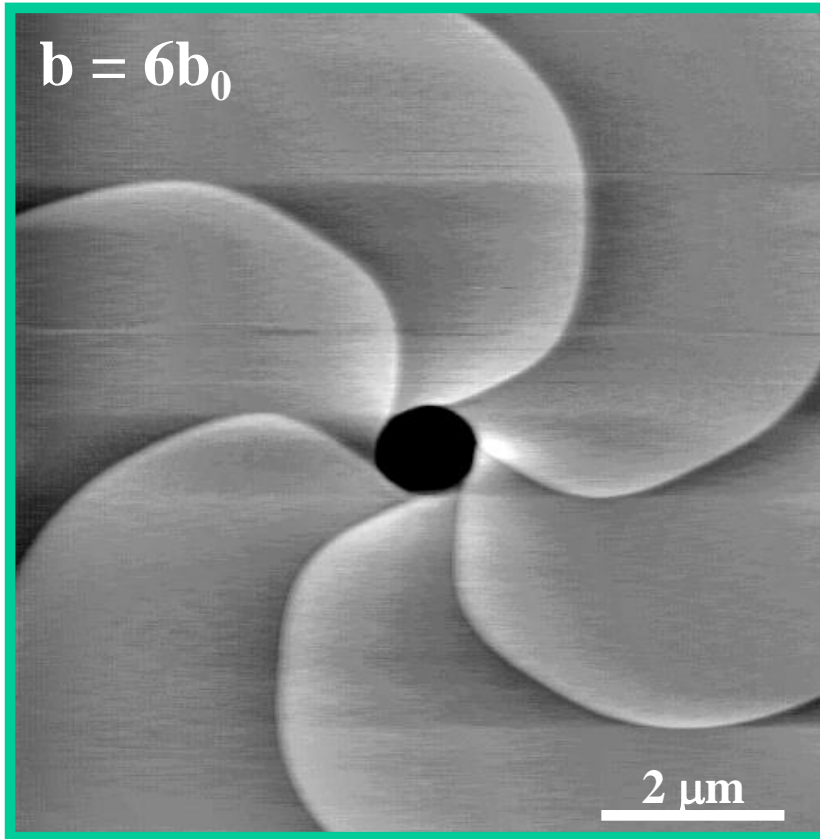


SiC: Wafer Price vs. Year





Defects: Micropipes

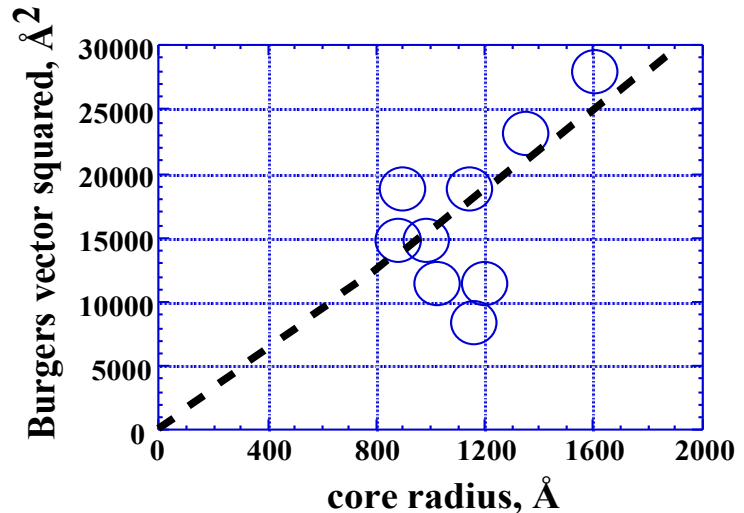


$$\frac{b^2}{r_o} = \frac{8\pi^2 \gamma}{G}$$

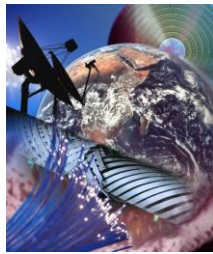
surface energy,
 $\gamma = 4 \text{ J/m}^2$

$$\frac{b^2}{r_o} = 16 \text{ \AA}$$

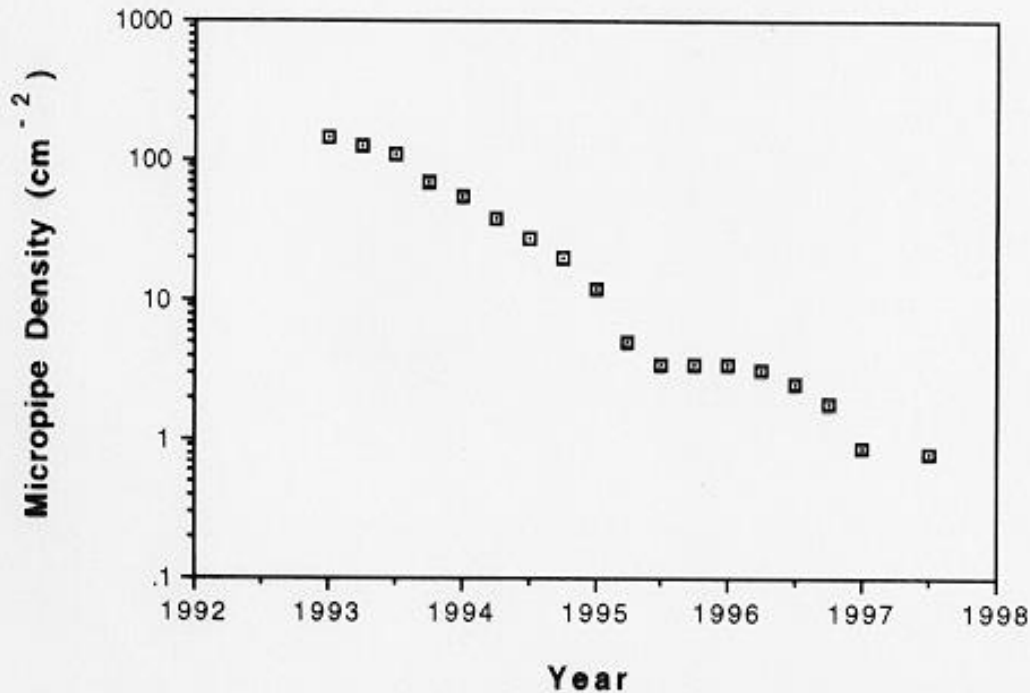
shear modulus,
 $G = 200 \text{ GPa}$



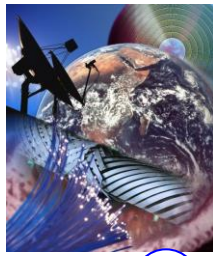
Micropipes form to relieve strain around super-screw dislocations.



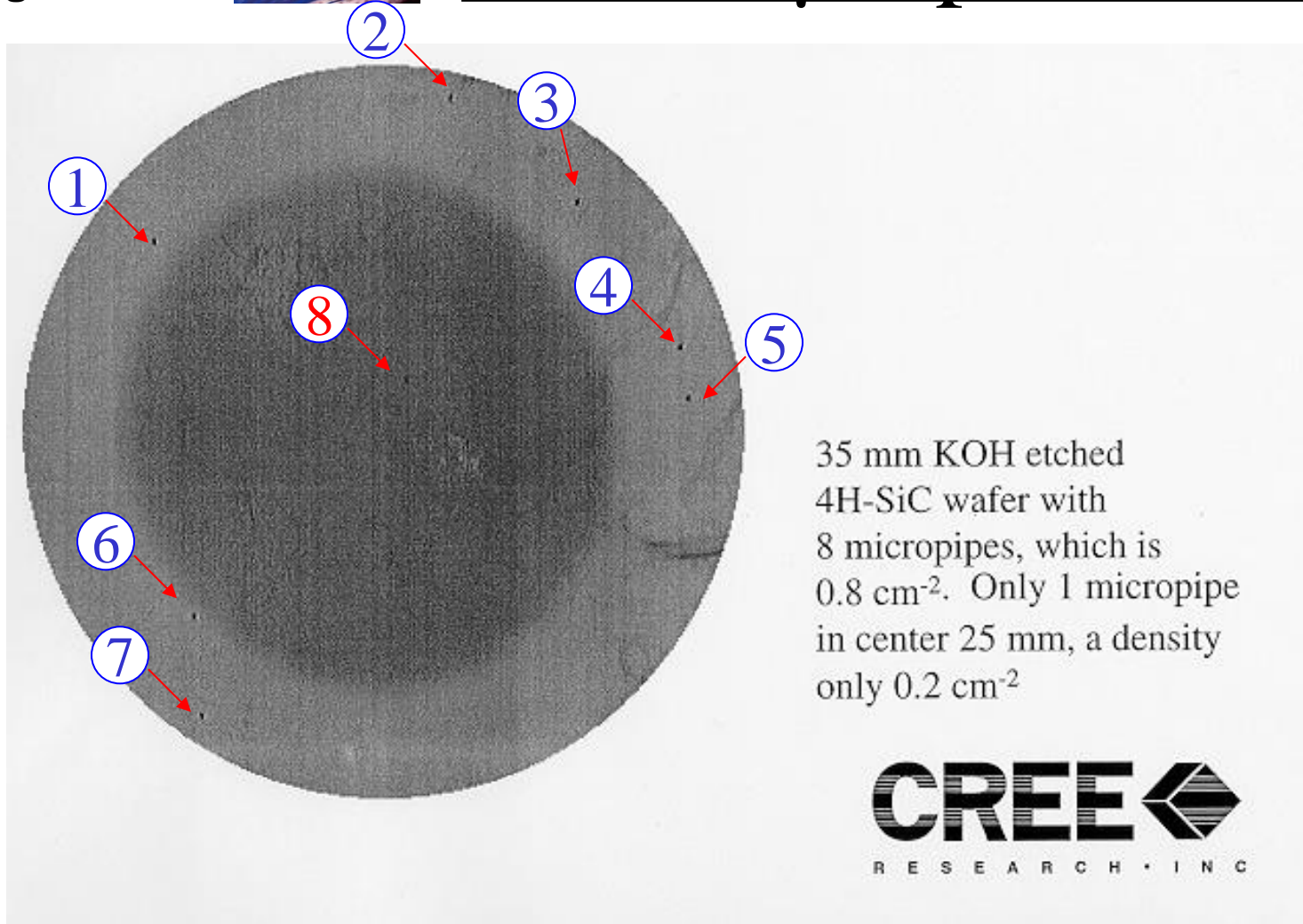
SiC: Micropipe Density vs. Year

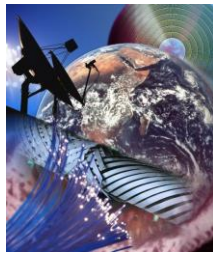


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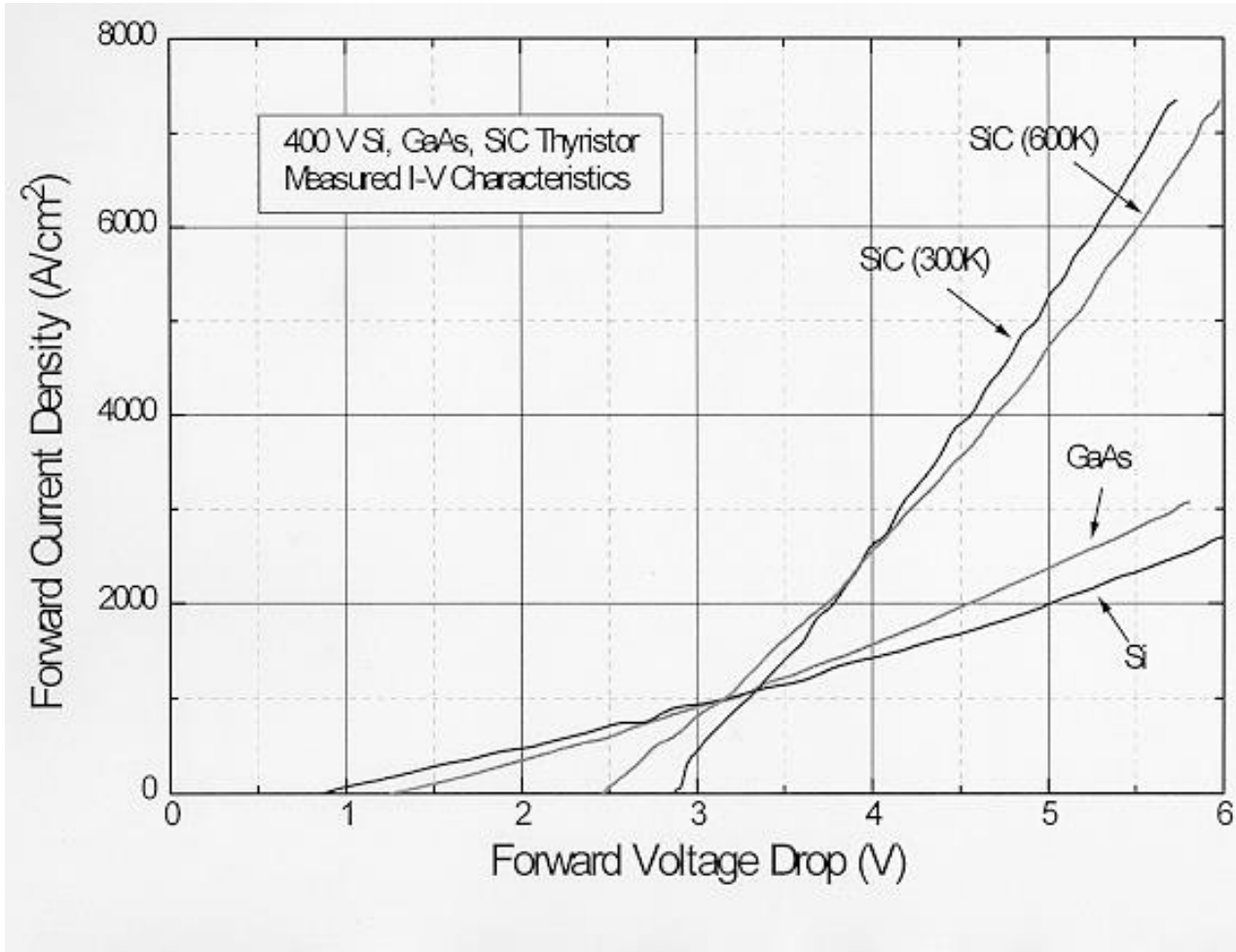


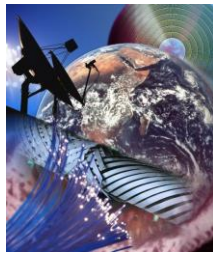
SiC: Record μ Pipe Density



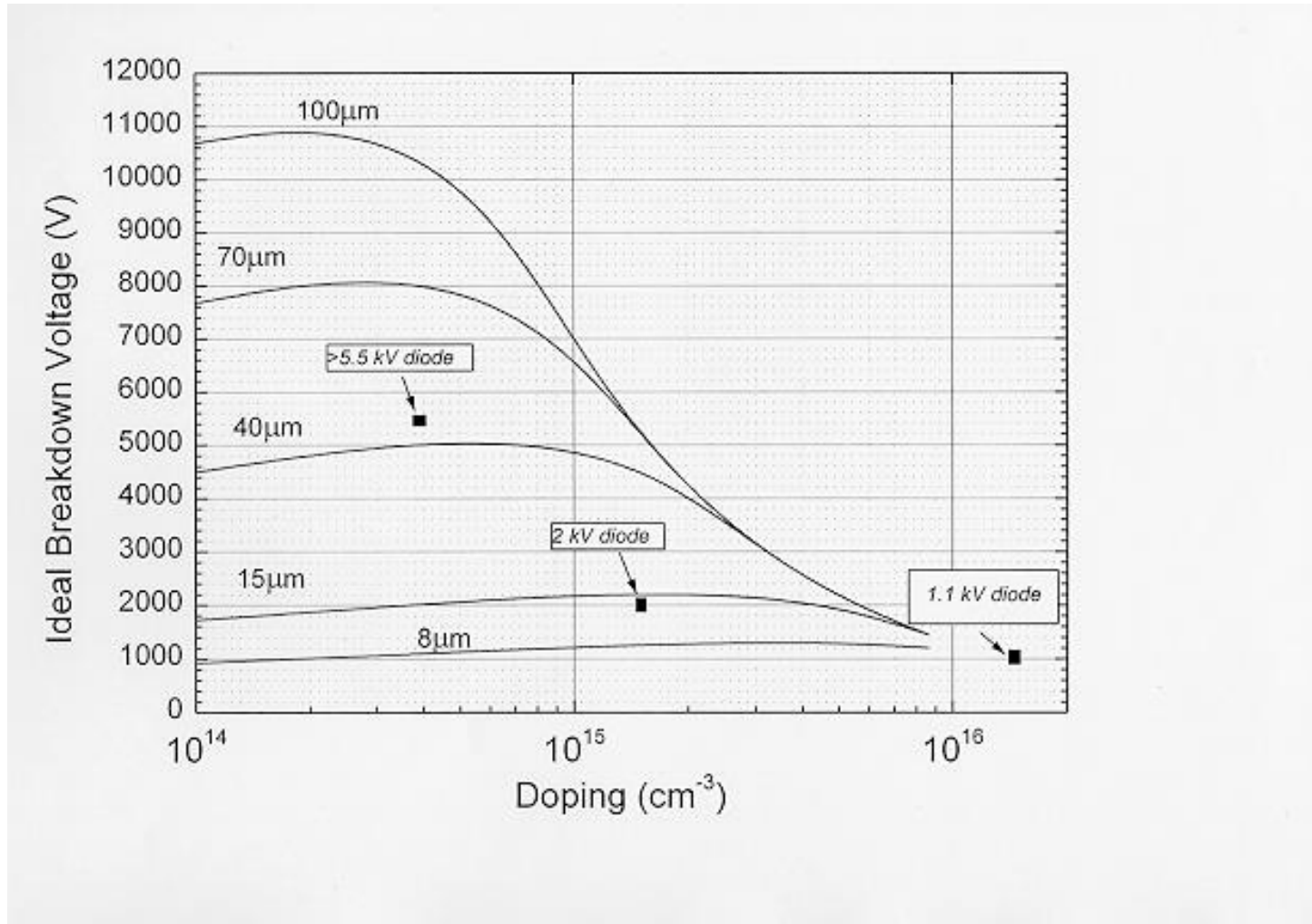


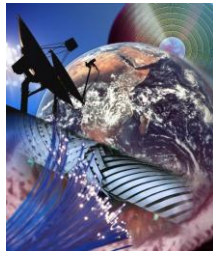
SiC Thyristor: Forward Voltage





SiC Diode: Reverse Characteristics





What About GaN & Diamonds?

See OutPost 8

“Why Diamonds are a Girl’s Best Friend!”